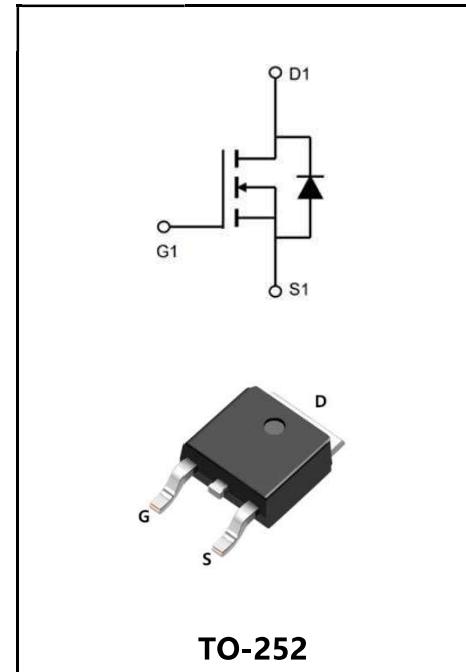


200V N-CHANNEL ENHANCEMENT MODE MOSFET
MAIN CHARACTERISTICS

I_D	9A
V_{DSS}	200V
R_{DS(on)-typ(@V_{GS}=10V)}	<300mΩ(Type:250mΩ)


Application

- ◆ Battery protection
- ◆ Load switch
- ◆ Uninterruptible power supply

Mechanical Data

- ◆ Case: Molded plastic
- ◆ Mounting Position: Any
- ◆ Molded Plastic: UL Flammability Classification Rating 94V-0
- ◆ Solder bath temperature 275°C maximum, 10s per JESD22-106

Product Specification Classification

Part Number	Part Number	Marking	Pack
YFW9N20AD	TO-252	YFW 9N20AD XXXXX	2500PCS/Tape

Maximum Ratings at Tc=25°C unless otherwise specified

Characteristics	Symbols	Value	Units
Drain-Source Voltage	VDS	200	V
Gate-Source Voltage	VGS	±20	V
Continue Drain Current	ID	9	A
Pulsed Drain Current (Note1)	IDM	36	A
Power Dissipation(Tc = 25°C)	PD	74	W
Single Pulse Avalanche Energy (Note2)	EAS	100	mJ
Avalanche Current (note1)	IAR	7.5	A
Repetitive Avalanche Energy note1)	EAR	8.1	mJ
Operating Temperature Range	TJ	-55 to +150	°C
Storage Temperature Range	TSTG	-55 to +150	°C
Thermal Resistance, Junction to Case	RθJC	1.7	°C/W
Thermal Resistance, Junction to Ambient	RθJA	62.5	°C/W

Electrical Characteristics at Tc=25°C unless otherwise specified

Characteristics	Test Condition	Symbol	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	VGS = 0 V, ID = 250 μA	BVDS	200	222	-	V
Drain-Source Leakage Current TJ = 25°C	VDS = 200 V, VGS = 0 V	IDSS	-	-	5	uA
TJ = 125°C	VDS = 160 V, VGS = 0 V		-	-	100	
Gate Leakage Current	VGS = ± 20 V	IGSS	-	-	±100	nA
Gate-Source Threshold Voltage	VDS = VGS, ID = 250 μA	VGS(th)	1.0	1.6	3.0	V
Drain-Source On-State Resistance	VGS = 10 V, ID = 4.5A	RDS(on)	-	230	300	mΩ
Input Capacitance	VGS = 0 V, VDS = 25 V, f = 1MHz	Ciss	-	684	-	pF
Output Capacitance		Coss	-	103	-	
Reverse Transfer Capacitance		Crss	-	37	-	
Turn-on Delay Time(Note2)	ID = 9A, VDD = 100 V, RG = 25Ω	td(ON)	-	12	-	nS
Rise Time(Note2)		tr	-	22	-	
Turn-Off Delay Time(Note2)		td(OFF)	-	50	-	
Fall Time(Note2)		tf	-	48	-	
Total Gate Charge(Note2)	ID = 9 A, VDD = 160 V, VGS = 10 V	QG	-	23	-	nC
Gate to Source Charge(Note2)		QGS	-	2.5	-	
Gate to Drain Charge(Note2)		QGD	-	10	-	

Source-Drain Diode Characteristics at Ta=25°C unless otherwise specified

Characteristics	Test Condition	Symbol	Min.	Typ.	Max.	Unit
Maximum Body-Diode Continuous Current	$T_C = 25^\circ\text{C}$	I_S	-	-	9	A
Maximum Body-Diode Pulsed Current		I_{SM}	-	-	36	A
Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{SD} = 9 \text{ A}, T_J = 25^\circ\text{C}$	V_{SD}	-	-	1.4	V
Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_S = 9 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}$	t_{rr}	-	190	-	nS
Reverse Recovery Charge		Q_{rr}	-	1.7	-	μC

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
2. The EAS data shows Max. rating , IAS = 7.5A, VDD = 50V, RG = 25 Ω, Starting TJ = 25 °C
3. The test condition is Pulse Test: Pulse width ≤ 300μs, Duty Cycle ≤ 1%
4. The power dissipation is limited by 150°C junction temperature
5. The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

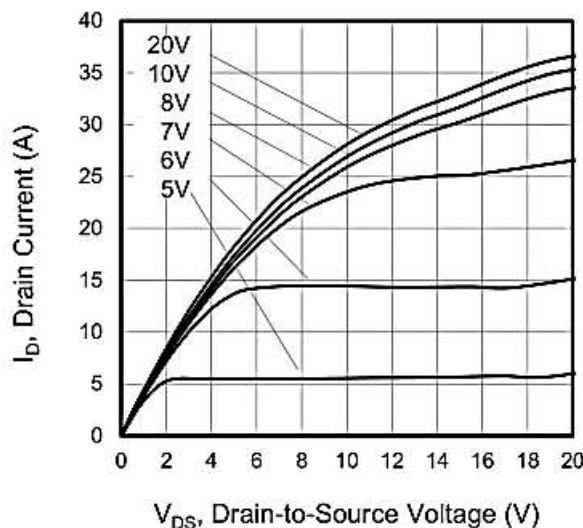
Ratings and Characteristic Curves


Figure 1. Output Characteristics ($T_J = 25^\circ\text{C}$)

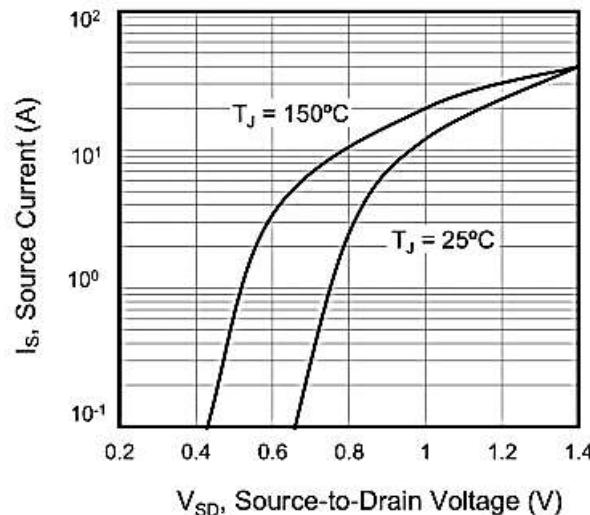


Figure 2. Body Diode Forward Voltage

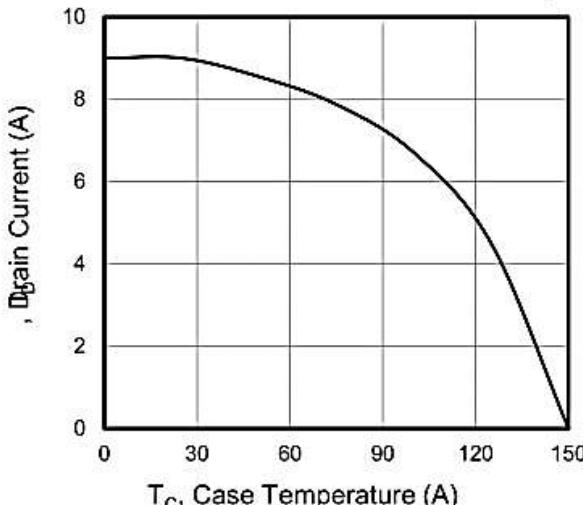


Figure 3. Drain Current vs. Temperature

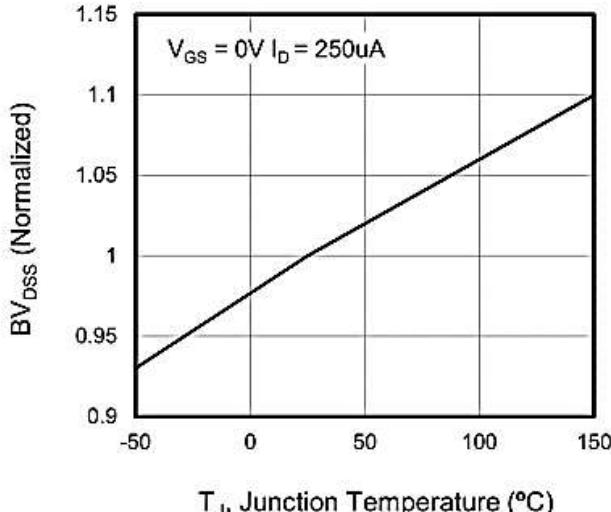


Figure 4. BV_{DSS} Variation vs. Temperature

Ratings and Characteristic Curves

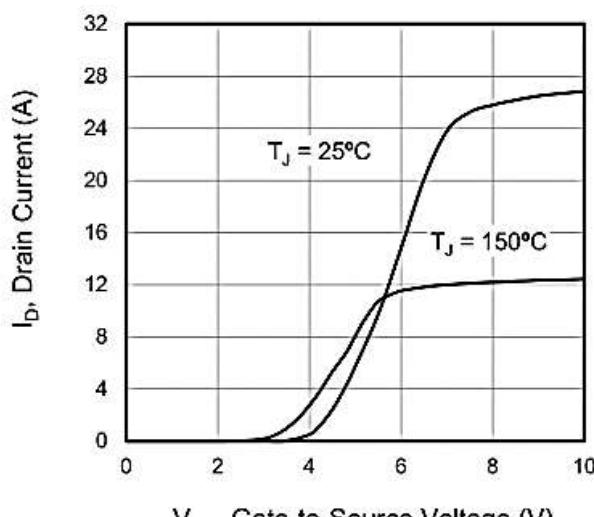


Figure 5. Transfer Characteristics

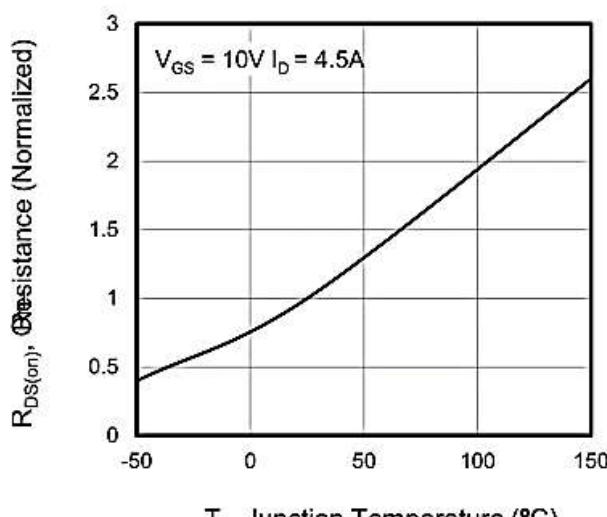


Figure 6. On-Resistance vs. Temperature

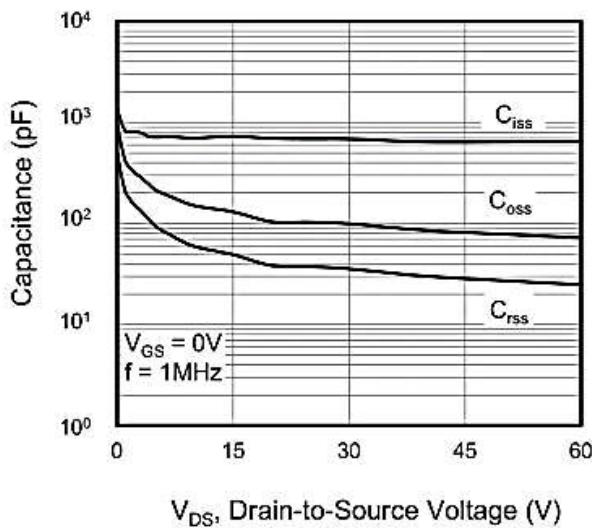


Figure 7. Capacitance

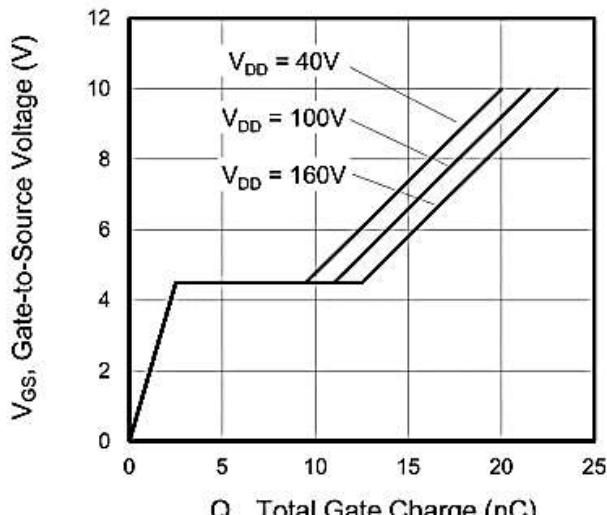


Figure 8. Gate Charge

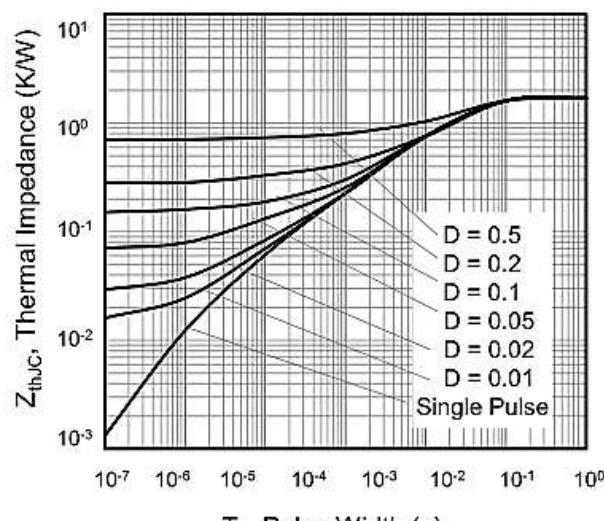


Figure 10. Transient Thermal Impedance

Package Outline Dimensions millimeters

TO-252

DETAIL A

DETAIL A

Dim.	Min.	Typ.	Max.
A	2.10	-	2.50
A2	0	-	0.10
B	0.66	-	0.86
B2	5.18	-	5.48
C	0.40	-	0.60
C2	0.44	-	0.58
D	5.90	-	6.30
D1	5.30REF		
E	6.40	-	6.80
E1	4.63	-	-
G	4.47	-	4.67
H	9.50	-	10.70
L	1.09	-	1.21
L2	1.35	-	1.65
V1	-	7°	-
V2	0°	-	6°

All Dimensions in millimeter